

CSC THERMAL CONDUCTIVE PAD

TP-S2000 Series

Description & Applications

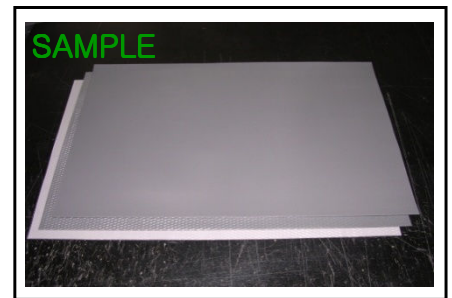
TP-S2000 gel type is recommended for low stress applications that require a mid to high thermally conductive interface material. The conformable nature allows the pad to fill in air voids and air gaps between main boards and metal chassis with stepped topography, high stack-up tolerances.

- Set-top Boxes (SD/HD)
- Mass Storage Devices (CDROM/DVD)
- Graphic Cards and Processors



Main Features

- Thermal conductivity = 2.0 W/mK
- Self sticky properties
- Conformable low hardness
- Electrically insulating



Specifications

ITEM	TP-S2000	METHOD
Mechanical		
Color*	Gray	Visual
Thickness (mm)	0.1 ~ 5.0	ASTM D374
Density (g/cc)	2.5	ASTM D792
Hardness (Shore 00)	10	ASTM D2240
Tensile Strength (kgf/cm ²)	2	ASTM D412
Use Temp. (°C)	-60 ~ 200	-
Electrical		
Dielectric Breakdown Voltage (V)	> 6,000	ASTM D149
Volume Resistivity (Ω · cm)	10 ¹³	ASTM D257
Thermal		
Thermal Conductivity (W/mK)	2.0	ASTM C518-98 (Modified)
Flame Rating (UL94)	V-0	File No. E258204

※ Pad color can be adjustable upon request